

**IN THE CLAIMS**

1. (canceled)

2. (canceled)

3. (canceled)

4. (canceled)

5. (currently amended) The microelectronic assembly as claimed in claim ~~±~~ 9, wherein said first microelectronic element is selected from the group consisting of a semiconductor chip, a semiconductor wafer, a semiconductor chip package ~~having a dielectric element attached to a chip~~, a circuit board, a dielectric sheet, a circuit panel, a connection component, an interposer, a substrate and a dielectric substrate.

6. (currently amended) The microelectronic assembly as claimed in claim ~~±~~ 9, wherein said second microelectronic element is selected from the group consisting of a semiconductor chip, a semiconductor wafer, a semiconductor chip package ~~having a dielectric element attached to a chip~~, a circuit board, a dielectric sheet, a circuit panel, a connection component, an interposer, a substrate and a dielectric substrate.

7. (currently amended) The microelectronic assembly as claimed in claim ~~±~~ 9, wherein said first microelectronic element includes a semiconductor wafer comprising a plurality of semiconductor chips, said wafer being severable for providing individual packages comprising one or more of said semiconductor chips electrically interconnected with at least a region of said second microelectronic element.

8. (currently amended) The microelectronic assembly as claimed in claim ~~±~~ 9, wherein said at least one ~~flexible~~ lead comprises an array of flexible leads extending between and

electrically interconnecting said first and second microelectronic elements.

9. (new) A microelectronic assembly comprising:

a first microelectronic element having a contact bearing face and at least one contact accessible at the contact bearing face;

a second microelectronic element opposing said first microelectronic element, said second microelectronic element having a first surface including at least one lead extending over the first surface;

a first fusible material engaging the at least one contact of said first microelectronic element;

a second fusible material engaging the at least one lead, wherein one of said first and second fusible materials has a higher melting temperature and one of said first and second fusible materials has a lower melting temperature;

said first and second microelectronic elements being juxtaposed with one another so that said first and second fusible materials are in substantial alignment with one another, wherein one of said first and second fusible materials is in a liquid state and one of said first and second fusible materials is in a solid state.

10. (new) The microelectronic assembly as claimed in claim 9, wherein said first and second fusible materials are spaced from one another.

11. (new) The microelectronic assembly as claimed in claim 9, wherein said first and second fusible materials are conductive.

12. (new) The microelectronic assembly as claimed in claim 9, wherein said first and second fusible materials are connectable together for electrically interconnecting said first and second microelectronic elements.

13. (new) The microelectronic assembly as claimed in claim 9, wherein the at least one lead has a first end permanently attached to said second microelectronic element and a second end releasably attached to said second microelectronic element.

14. (new) The microelectronic assembly as claimed in claim 9, wherein the at least one lead overlies the first surface of said second microelectronic element.

15. (new) The microelectronic assembly as claimed in claim 9, wherein the at least one lead is flexible.

16. (new) A microelectronic assembly comprising:  
a first microelectronic element having a contact bearing face and at least one contact accessible at said contact bearing face;  
a second microelectronic element juxtaposed with said first microelectronic element, said second microelectronic element having a first surface and at least one lead overlying said first surface;  
a first conductive mass disposed on said at least one contact of said first microelectronic element, said first conductive mass having a first melting temperature; and  
a second conductive mass disposed on said at least one lead, said second conductive mass having a second melting temperature that is different than said first melting

temperature, wherein said first and second conductive masses are spaced from one another.

17. (new) The microelectronic assembly as claimed in claim 16, wherein said first and second conductive masses are in alignment with one another.

18. (new) The microelectronic assembly as claimed in claim 16, wherein one of said first and second conductive masses is in a liquid state and one of said first and second conductive masses is in a solid state.

19. (new) The microelectronic assembly as claimed in claim 16, wherein said first and second conductive masses are fusible together for electrically interconnecting said at least one contact of said first microelectronic element and said at least one lead of said second microelectronic element.

20. (new) The microelectronic assembly as claimed in claim 16, wherein said at least one lead has a first end that is permanently attached to said second microelectronic element and a second end that movable away from said first surface of said second microelectronic element.

21. (new) The microelectronic assembly as claimed in claim 20, wherein said second conductive mass is disposed on said second end of said lead.

22. (new) The microelectronic assembly as claimed in claim 20, wherein said lead is flexible and said second end of said lead is releasably attached to the first surface of said second microelectronic element.

23. (new) A microelectronic assembly comprising:

a first microelectronic element having a contact bearing face and one or more contacts provided at the contact bearing face;

a second microelectronic element juxtaposed with said first microelectronic element, said second microelectronic element having a first surface including one or more conductive pads;

one or more conductive masses electrically interconnecting the contacts of said first microelectronic element and the conductive pads of said second microelectronic element, wherein each said conductive mass includes a first region comprising a first fusible material transformable from a solid to a liquid at a first melting temperature and a second region comprising a second fusible material transformable from a solid to a liquid at a second melting temperature that is less than the first melting temperature; and

at least one flexible lead extending between and electrically interconnecting said first and second microelectronic elements, wherein said first microelectronic element includes a semiconductor wafer comprising a plurality of semiconductor chips, said wafer being severable for providing individual packages comprising one or more of said semiconductor chips electrically interconnected with at least a region of said second microelectronic element.